

# **DICING SAW - DISCO DAD3220**



These instructions are intended for reference only, and will *not* replace the thorough training required for proper system operation. Contact a clean room staff member with questions or to report a system problem.

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| 4. | NON-CONTACT SETUP:<br>Perform non-contact alignment<br>to calibrate the height of the<br>blade and to measure how much<br>the blade has been consumed.<br>Wait for 10 min or longer to let<br>the spindle rotate before<br>performing the setup.<br>Click 'Blade Maintenance',<br>'Blade Setup', and 'Non-<br>Contact'. Press 'Start'. Once set<br>up is completed, check the<br>measured value to see if the<br>blade needs to be replaced.<br>Contact superuser or clean room<br>staff for the blade replacement.<br>Click 'EXIT' | F3       F4       Source       Source       Operator         Device       Data       F4       Source       Operator         Maintenance       F4       Source       Operator         Maintenance       F4       Source       Operator         Maintenance       F4       Source       Hairtine         Blade       Blade       F4       Source       Hairtine         Blade       Blade       F4       Source       Hairtine         Blade       Blade       F4       Source       Hairtine         Blade       F2       Source       Source       F4       Source       Source |
|----|---|---|
| 5. | MOUNT YOUR SAMPLE:<br>Dots on the white ring are facing<br>up. Place the sticky side of the<br>UV tape over the white ring.<br>Then, press the blue ring over<br>the tape. Dots on the blue ring<br>should be aligned with those on<br>the white ring. Cut the extra<br>tape outside of the grip rings.<br>Remember to put UV tape back<br>to the cabinet to keep out of<br>light.  |   |





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|   | Place your wafer at the center of<br>the assembly. The alignment<br>marks side should be facing up.<br>You can also use the stainless<br>steel mounting ring.<br>Remove bubbles from the<br>backside of the tape.                  |  |
|---|--|--|
| 6 | <ul> <li>LOAD SAMPLE:<br/>Open the door and place your<br/>wafer/sample at the center of<br/>the chuck.</li> <li>Close the door and turn on the<br/>C/T vacuum.</li> <li>Check the green light of the<br/>vacuum gauge.</li> </ul> | <image/>                                   |
|   |  | C/T Vacuum                                 |
| 7 | . HAIRLINE ALIGNMENT<br>(OPTIONAL):  | F3 F4 F5                                   |
|   | Click 'Blade Maintenance' and<br>then, 'Hairline Alignment'.   | Blade<br>Setup Dress Hairline<br>Alignment |
|   | Click 'Focus'. On the 'Focus<br>Adjustment' page, click 'Auto<br>Focus' and then, 'EXIT' the page.   | F8 F8 AT C                                 |





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To align your sample, find the first alignment mark or the reference point on the left side of the sample. Click 'Align O'. The head will move to the right side of the sample. Find the second alignment mark and then, press 'Align O' again.

You can move the head around by pressing the scan arrows or by touching the screen with the pen.

Once your sample is aligned, you can move to the test area or the position where you want to have the first cut.

You have to give "Work size" larger than the actual size of the sample to avoid breaking the blade. For other dicing parameters, please see **step 8**.

Click 'ENTER' to save the parameter changes. Press 'START'. The machine will cut one line.

Use 'Narrow Hair' and 'Widen Hair' keys to adjust the hairline width. Click 'ENTER' and then, 'EXIT' the page.





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**DEFINE YOUR PROCESS:** 8. Press "Device Data". Go to your group's folder and choose your recipe. Set the workpiece size: to avoid breaking the blade it has to be a number larger than the dimensions of your sample (at least 20 mm larger). Work thickness is your wafer thickness. Make sure the blade is correct for your thickness. Tape thickness is 0.070 mm. Ch1 is the horizontal cuts, and Ch2 is the vertical cuts. Cut dir. 'REAR' means it cuts front to rear, so you define the first cut in the front of the wafer. "Cut" is the number of cuts. Leave the last three as 0.

> Check spindle speed: 30,000 rpm works for Si and 10,000 rpm for glass. Type the cutting ch seq. as 1 for O horizontal cuts and 12 for both horizontal and vertical cuts.

Ch1 SEQ1: Set "Blade height" 0.050 to cut all the way through the wafer and 0.02 mm through the tape. Remember y=0 at the bottom of the tape. Feed speed



| Round        |     | 120.000 | mm |
|--------------|-----|---------|----|
| C Square     | Ch1 | 50.000  | mm |
| l            | Ch2 | 50.000  | mm |
| Work Thickne | ess | 0.550   | mm |
| Tape Thickne | ess | 0.070   | mm |

|          | Ch 1   |       | Ch 2<br>90.000 ° |       |
|----------|--------|-------|------------------|-------|
| θ Deg.   |        |       |                  |       |
| Cut mode | A      | -     | A                | -     |
| Cut dir. | REAR   | -     | REAR             | -     |
| Cut      | 9      | lines | 9                | lines |
| Offset Y | 0.0000 |       | 0.0000           |       |
| Noncut F | 0.000  |       | 0.000            |       |
| Noncut R | 0.000  |       | 0.000            |       |

|              | Spindle rev.<br>Precut process No.<br>Cutting ch seq. |        |        | 30000<br>0<br>12 | /min   |
|--------------|---|--------|--------|------------------|--------|
|              | Ch 1  |        |        | Ch 2             |        |
|              | SEQ1  | SEQ2   | SEQ3   | SEQ1             | SEQ2   |
| Blade height | 0.050   | 0.000  | 0.0    | 0.050            | 0.000  |
| Feed speed   | 20.000  | 0.000  | 0.0    | 20.000           | 0.000  |
| Y-index      | 10.0000   | 0.0000 | 0.00   | 10.0000          | 0.0000 |
| Repeat times | 0   | 0      | IT/EUA | 0                | 0      |





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|                       | of 20-30 mm/sec should be fine<br>for silicon and 5-10 mm/sec for<br>glass. Enter y-index (pitch/<br>spacing between cuts). Leave all<br>other sequences (e.g., SEQ2) set<br>to 0 unless you want irregular<br>spacing.   |  |  |  |
|-----------------------|---|--|--|--|
| 9.                    | RUN PROCESS:<br>Press "ENTER" to save and "Full<br>Auto".<br>On the 'Full Automation' page,<br>click 'Manual Align'. Check lights<br>are on (DIR ~ 15% usually works).<br>Place Hairline (crosshair) on<br>street edge or left alignment<br>mark and press 'Align O', the<br>machine will move to the right,<br>move the same hairline to same<br>street edge or right alignment<br>mark and press 'Align O' again.<br>The machine moves back to the<br>left. Read messages at the top<br>while doing this. Move to the<br>position where you want to have<br>the first <u>horizontal</u> cut.<br>Press 'ENTER'.<br>*If you get an error 'press<br>underlined y-axis', try selecting<br>the wafer icon and jumping by | Spindle rev.       30000 /min         Precut process No.       0         Ch 1       Ch 2         SE01       SE02         0.000       0.000 |  |  |
| CNI Shared Facilities |   |  |  |  |

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one index up and then, back to where your first cut was. Now 'ENTER' should work.

The machine will then rotate to the degree specified in the program. Do 'Align  $\Theta$ ' as per Ch1. Move to the position where you want to have the first <u>vertical</u> cut.

Press 'ENTER' and then, 'START'.

The machine will start dicing. Monitor the current while it cuts.

\*If you want to pause at the end of the current cut – press 'STOP' on the top right. If you want to pull up the blade immediately press 'Z-EM' on the top left.

#### **10 RETRIEVE SAMPLE:**

Open the door and blow water off from the frame – careful not to alarm.

Turn off the C/T vacuum and take the frame out. Blow water off the chuck. Close the door.

Cut your sample out of tape. Remove tape from the frame. Dry the frame rings.











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| 11. | RETURN TO NORMAL:<br>Do blade setup non-contact<br>alignment (see step 4).<br>Press 'System Initial'. Check no<br>parts are on the chuck. When<br>done initializing, turn key to off. | NE MORECONE                                |
|-----|---|--|
| 12. | <b>BADGER LOGOUT:</b><br>Don't forget to disable the tool<br>in badger after you're done.   | Equipment Actions       Res         Enable |

# DICING SAW - DISCO DAD3220 Blade Change Procedure

| 13. | <b>BADGER:</b><br>Enable the tool in badger  |  |
|-----|--|--|
| 14. | <b>START THE SYSTEM:</b><br>Turn the key to start dicing saw.<br>Wait for the system to boot up.<br>Press 'System Initial'. Wait for<br>the message to say,<br>"Initialization completed".                         | Blade Setup<br>Device Data<br>System Initial                               |
| 15. | <b>BLADE REPLACEMENT (1):</b><br>Press 'Blade Maintenance' and<br>'Blade Replacement'. Wait for<br>the spindle to be off if it was<br>already on.  | F3<br>Device<br>Data<br>Blade<br>Maintenance<br>Blade Maintenance<br>(4.0) |
|     | The head will then move<br>forward. Open the guard door.<br>Unscrew a pin and take part out<br>(marked as a red circle). Hold it<br>with your left hand while<br>unscrewing a pin. It is a very<br>delicate piece. | F1<br>Blade<br>Replacement   |



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| Press 'ENTER' to save the<br>changes and 'EXIT'. The machine<br>will show 'Confirm jig has <u>been</u><br><u>removed</u> . If OK, press button to<br>continue.' Press 'EXIT' again to<br>accept.  |                                 |
|---|---------------------------------|
| <ul> <li>19. NON-CONTACT SETUP:<br/>Perform non-contact alignment<br/>to calibrate the height of the<br/>blade.</li> <li>Turn on 'Spindle'. Wait for 10<br/>min or longer to let the spindle<br/>rotate before performing the<br/>setup.</li> <li>Click 'Blade Maintenance',<br/>'Blade Setup', and 'Non-<br/>Contact'. Press 'Start'. Once set<br/>up is completed, click 'EXIT'.</li> <li>*At this point, a user can<br/>continue the work from step 5<br/>on the SOP.</li> <li>Press 'System Initial'. When done<br/>initializing, turn key to off.</li> </ul> | <complex-block></complex-block> |
| <b>20. BADGER LOGOUT:</b><br>Don't forget to disable the tool<br>in badger after you're done.   |                                 |